

ABSTRACT

A photocurable and thermosetting composition which is useful in forming a matte film and can be developed with an aqueous alkaline solution is provided. The composition comprises (A) a photosensitive prepolymer obtained by causing a saturated or unsaturated polybasic acid anhydride to react with a hydroxyl group of an esterification product of a novolak type epoxy compound and an unsaturated monocarboxylic acid, (B) a carboxyl group-containing copolymer resin, (C) a photopolymerization initiator, (D) a diluent, (E) a polyfunctional epoxy compound having at least two epoxy groups in its molecule, and, when necessary, (F) an inorganic filler. The composition may further comprise (G) an epoxy resin curing agent. This composition can be advantageously used for the formation of a solder resist on a printed circuit board.



162162



G00002